

### Features

- Operating voltage: +5.0V
- Programming voltage
- $V_{PP}=12.5V\pm0.2V$
- V<sub>CC</sub>= $6.0V\pm0.2V$
- High-reliability CMOS technology
- Latch-up immunity to 100mA from -1.0V to  $V_{CC}\mbox{+}1.0V$
- CMOS and TTL compatible I/O
  - Low power consumption
  - Active: 30mA max.
  - Standby: 1µA typ.
- 256K×8-bit organization

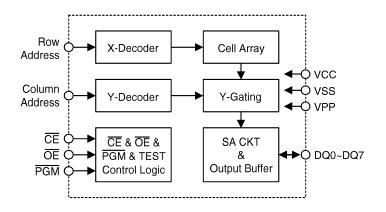
### **General Description**

The HT27C020 chip family is a low-power, 2048K (2,097,152) bit, +5V electrically one-time programmable (OTP) read-only memories (EPROM). Organized into 256K words with 8 bits per word, it features a fast single address location programming, typically at  $75\mu$ s per byte. Any byte can be accessed in less than

- Fast read access time: -70ns, -90ns and -120ns
- Fast programming algorithm
- Programming time 75µs typ.
- Two line controls ( $\overline{OE}$  and  $\overline{CE}$ )
- Standard product identification code
- Package type
  - 32-pin DIP/SOP
  - 32-pin PLCC
- Commercial temperature range (0°C to +70°C)

70ns/90ns/120ns with respect to Spec. This eliminates the need for WAIT states in high-performance microprocessor systems. The HT27C020 has separate Output Enable ( $\overline{OE}$ ) and Chip Enable ( $\overline{CE}$ ) controls which eliminate bus contention issues.

### **Block Diagram**

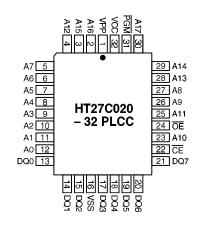


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## **Pin Assignment**

	<u> </u>		
VPP 🗆	11	32	
A16 🗆	2	31	D PGM
A15 🗆	з	30	🗆 A17
A12 🗆	4	29	🗆 A14
A7 🗆	5	28	🗆 A13
A6 🗆	6	27	🗆 A8
A5 🗆	7	26	🗆 A9
A4 🗆	8	25	🗆 A11
A3 🗆	9	24	
A2 🗆	10	23	<b>A</b> 10
A1 🗆	111	22	
A0 🗆	12	21	
	13	20	
DQ1 🗆	14	19	
DQ2	15	18	
VSS 🗆	16	17	
	HT27C	220	I
			_
-	32 DIP/	'SO	Ρ



## **Pin Description**

Pin Name	I/O/C/P	Description
A0~A17	Ι	Address inputs
DQ0~DQ7	I/O	Data inputs/outputs
CE	C	Chip enable
ŌĒ	C	Output enable
PGM	С	Program strobe
NC	_	No connection
VPP	Р	Program voltage supply
VCC	Ι	Positive power supply
VSS	Ι	Negative power supply

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## **Absolute Maximum Rating**

Operation Temperature Commercial	0°C to +70°C
Storage Temperature	–65°C to 125°C
Applied VCC Voltage with Respect to VSS	–0.6V to 7.0V
Applied Voltage on Input Pin with Respect to VSS	–0.6V to 7.0V
Applied Voltage on Output Pin with Respect to VSS	0.6V to V <sub>CC</sub> +0.5V
Applied Voltage on A9 Pin with Respect to VSS	–0.6V to 13.5V
Applied VPP Voltage with Respect to VSS	–0.6V to 13.5V
Applied READ Voltage (Functionality is guaranteed between these limits)	+4.5V to +5.5V

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

## **D.C. Characteristics**

### Read operation

Symbol	Parameter		Test Conditions	Min	Trom	Max.	Unit
	Farameter	Vcc	Conditions	I <b>VIIII.</b>	Тур.	Max.	Unit
Vон	Output High Level	5V	I <sub>OH</sub> =-0.4mA	2.4	_	_	V
VOL	Output Low Level	5V	I <sub>OL</sub> =2.1mA	—	_	0.45	v
V <sub>IH</sub>	Input High Level	5V	—	2.0	_	V <sub>CC</sub> +0.5	V
VIL	Input Low Level	5V	—	-0.3	_	0.8	V
ILI	Input Leakage Current	5V	V <sub>IN</sub> =0 to 5.5V	-5	_	5	μA
ILO	Output Leakage Current	5V	V <sub>OUT</sub> =0 to 5.5V	-10	_	10	μA
Icc	VCC Active Current	5V	TE=V <sub>IL</sub> , f=5MHz, I <sub>OUT</sub> =0mA	_	- $ -$ 30		mA
I <sub>SB1</sub>	Standby Current (CMOS)	5V	$\overline{CE} = V_{CC} \pm 0.3V$	- 1.0 10		10	μA
I <sub>SB2</sub>	Standby Current (TTL)	5V	$\overline{CE}=V_{IH}$	_	_	1.0	mA
I <sub>PP</sub>	VPP Read/Standby Current	5V	$\overline{CE} = \overline{OE} = V_{IL}, V_{PP} = V_{CC}$	_	_	100	μΑ

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## **Programming operation**

Symbol	Parameter	Т	est Conditions	Min.	Tun	Max.	Unit	
Symbol	r al ameter	Vcc	Conditions	IVIIII.	Тур.	Max.	Unit	
VOH	Output High Level	6V	I <sub>OH</sub> =-0.4mA	2.4		—	V	
Vol	Output Low Level	6V	IoL=2.1mA	—		0.45	V	
VIH	Input High Level	6V	_	0.7Vcc	_	Vcc+0.5	v	
VIL	Input Low Level	6V	_	-0.5	_	0.8	v	
ILI	Input Load Current	6V	V <sub>IN</sub> =V <sub>IL</sub> , V <sub>IH</sub>	_	_	5.0	μΑ	
VH	A9 Product ID Voltage	6V		11.5	_	12.5	V	
ICC	VCC Supply Current	6V	_			40	mA	
I <sub>PP</sub>	VPP Supply Current	6V	$\overline{CE}=V_{IL}$		_	10	mA	

### Capacitance

Symbol	Parameter	Т	est Conditions	Min.	Tron	Max.	Unit
	Farameter	Vcc	Conditions	IVIIII.	Тур.	Max.	Unit
C <sub>IN</sub>	Input Capacitance	5V	$V_{IN}=0V$	_	8	12	pF
COUT	Output Capacitance	5V	V <sub>OUT</sub> =0V	_	8	12	pF
CVPP	VPP Capacitance	5V	VPP=0V	—	18	25	pF

# A.C. Characteristics

## Read operation

Symbol	Parameter	Test	Conditions	-70		-90		-120		Unit
Symbol	I al ameter	Vcc	Conditions	Min.	Max.	Min.	Max.	Min.	Max.	om
t <sub>ACC</sub>	Address to Output Delay	5V	$\overline{CE} = \overline{OE} = V_{IL}$	_	70		90		120	ns
t <sub>CE</sub>	Chip Enable to Output Delay	5V	OE=VIL	_	70		90	_	120	ns
toE	Output Enable to Output Delay	5V	CE=VIL		30	_	35		40	ns
tDF	CE or OE High to Output Float, Whichever Occurred First	5V		_	25	_	25	_	30	ns
t <sub>OH</sub>	Output Hold from Address, CE or OE, Whichever Occurred First	5V	_	0	_	0		0	_	ns

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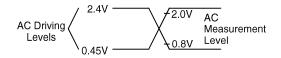
### **Programming operation**

#### $Ta=+25^{\circ}C\pm5^{\circ}C$

Symbol	Parameter	Tes	st Conditions	Min.	Trom	Max.	Unit	
Symbol	Farameter	Vcc	Vcc Conditions		тур.	wax.	Umt	
t <sub>AS</sub>	Address Setup Time	6V	—	2	_	_	μs	
toes	OE Setup Time	6V	—	2	_	_	μs	
t <sub>DS</sub>	Data Setup Time	6V	—	2	_	_	μs	
t <sub>AH</sub>	Address Hold Time	6V	_	0	_	_	μs	
tDH	Data Hold Time	6V	_	2	_	_	μs	
t <sub>DFP</sub>	Output Enable to Output Float Delay	6V	_	0	_	130	ns	
tvps	VPP Setup Time	6V	_	2	_	_	μs	
t <sub>PW</sub>	<b>PGM</b> Program Pulse Width	6V	_	30	75	105	μs	
t <sub>VCS</sub>	VCC Setup Time	6V	_	2	_	_	μs	
tCES	CE Setup Time	6V	_	2	_	_	ns	
t <sub>OE</sub>	Data Valid from $\overline{OE}$	6V	_	_	_	150	μs	
t <sub>PRT</sub>	VPP Pulse Rise Time During Programming	6V	_	2	_	—	μs	

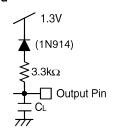
### Test waveforms and measurements

For -70, -90, -120 devices:



 $t_R$ ,  $t_F$ < 20ns (10% to 90%)

### Output test load



Note:  $C_L$ =100pF including jig capacitance, except for the -45 devices, where  $C_L$ =30pF.

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### **Functional Description**

#### Programming of the HT27C020

When the HT27C020 is delivered, the chip has all 2048K bits in the "ONE", or HIGH state. "ZEROs" are loaded into the HT27C020 through programming.

The programming mode is entered when  $12.5\pm0.2V$  is applied to the VPP pin,  $\overline{OE}$  is at  $V_{IH}$ , and  $\overline{CE}$  and  $\overline{PGM}$  are  $V_{IL}$ . For programming, the data to be programmed is applied with 8 bits in parallel to the data pins.

The programming flowchart in Figure 3 shows the fast interactive programming algorithm. The interactive algorithm reduces programming time by using 30µs to 105µs programming pulses and giving each address only as many pulses as is necessary in order to reliably program the data. After each pulse is applied to a given address, the data in that address is verified. If the data is not verified, additional pulses are given until it is verified or until the maximum number of pulses is reached while sequencing through each address of the HT27C020. This process is repeated while sequencing through each address of the HT27C020. This part of the programming algorithm is done at V<sub>CC</sub>=6.0V to assure that each EPROM bit is programmed to a sufficiently high threshold voltage. This ensures that all bits have sufficient margin. After the final address is completed, the entire EPROM memory is read at V<sub>CC</sub>=V<sub>PP</sub>=5.25±0.25V to verify the entire memory.

#### Program inhibit mode

Programming of multiple HT27C020 in parallel with different data is also easily accomplished by using the Program Inhibit Mode. Except for  $\overline{CE}$ , all like inputs of the parallel HT27C020 may be common. A TTL low-level program pulse applied to an HT27C020  $\overline{CE}$  input with Vpp=12.5±0.2V,  $\overline{PGM}$  LOW, and  $\overline{OE}$  HIGH will program that HT27C020. A high-level  $\overline{CE}$  input inhibits the HT27C020 from being programmed.

#### Program verify mode

Verification should be performed on the programmed bits to determine whether they were correctly programmed. The verification should be performed with  $\overline{OE}$  and  $\overline{CE}$  at V<sub>IL</sub>, PGM at V<sub>IH</sub>, and VPP at its programming voltage.

#### Auto product identification

The Auto Product Identification mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and the type. This mode is intended for programming to automatically match the device to be programmed with its corresponding programming algorithm. This mode is functional in the  $25^{\circ}C\pm 5^{\circ}C$  ambient temperature range that is required when programming the HT27C020.

To activate this mode, the programming equipment must force  $12.0\pm0.5V$  on the address line A9 of the HT27C020. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from  $V_{IL}$  to  $V_{IH}$ , when  $A1\!=\!V_{IH}$ . All other address lines must be held at  $V_{IH}$  during Auto Product Identification mode.

Byte 0 (A0=V<sub>IL</sub>) represents the manufacturer code, and byte 1 (A0=V<sub>IH</sub>), the device code. For HT27C020, these two identifier bytes are given in the Operation mode truth table. All identifiers for the manufacturer and device codes will possess odd parity, with the MSB (DQ7) defined as the parity bit. When A1=V<sub>IL</sub>, the HT27C020 will read out the binary code of 7F, continuation code, to signify the unavailability of manufacturer ID codes.

#### Read mode

The HT27C020 has two control functions, both of which must be logically satisfied in order to obtain data at outputs. Chip Enable ( $\overline{CE}$ ) is the power control and should be used for device selection. Output Enable ( $\overline{OE}$ ) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t<sub>ACC</sub>) is equal to the delay from  $\overline{CE}$ 

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to output (t<sub>CE</sub>). Data is available at the outputs (t<sub>OE</sub>) after the falling edge of  $\overline{OE}$ , assuming the  $\overline{CE}$  has been LOW and addresses have been stable for at least t<sub>ACC</sub>-t<sub>OE</sub>.

### Standby mode

The HT27C020 has CMOS standby mode which reduces the maximum VCC current to  $10\mu A$ . It is placed in CMOS standby when  $\overline{CE}$  is at  $V_{CC}\pm0.3V$ . The HT27C020 also has a TTL-standby mode which reduces the maximum VCC current to 1.0mA. It is placed in TTL-standby when  $\overline{CE}$  is at  $V_{IH}$ . When in standby mode, the outputs are in a high-impedance state, independent of the  $\overline{OE}$  input.

#### **Two-line output control function**

To accommodate multiple memory connections, a two-line control function is provided to allow for:

- · Low memory power dissipation
- Assurance that output bus contention will not occur

It is recommended that  $\overline{CE}$  be decoded and used as the primary device-selection function, while

OE be made a common connection to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

#### System considerations

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1µF ceramic capacitor (high frequency, low inherent inductance) should be used on each device between VCC and VPP to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7µF bulk electrolytic capacitor should be used between VCC and VPP for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

Mode	CE	OE	PGM	<b>A0</b>	A1	A9	VPP	Output
Read	VIL	VIL	X (2)	Х	X	X	Vcc	Dout
Output Disable	V <sub>IL</sub>	$V_{\mathrm{IH}}$	Х	Х	X	X	V <sub>C</sub> C	High Z
Standby (TTL)	VIH	Х	X	Х	x	X	Vcc	High Z
Standby (CMOS)	$V_{CC\pm} 0.3V$	Х	X	Х	X	X	Vcc	High Z
Program	V <sub>IL</sub>	V <sub>IH</sub>	VIL	Х	X	X	VPP	D <sub>IN</sub>
Program Verify	VIL	VIL	VIH	Х	x	X	VPP	DOUT
Product Inhibit	VIH	Х	X	Х	X	X	VPP	High Z
Manufacturer Code (3)	V <sub>IL</sub>	VIL	X	VIL	VIH	V <sub>H</sub> (1)	Vcc	1C
Device Type Code (3)	VIL	VIL	X	VIH	VIH	V <sub>H</sub> (1)	Vcc	02

#### Operation mode truth table

All the operation modes are shown in the table following.

Notes: (1)  $V_H$  = 12.0V  $\pm$  0.5V

(2) X=Either V<sub>IH</sub> or V<sub>IL</sub>

(3) For Manufacturer Code and Device Code, A1=VIH, When A1=VIL, both codes will read 7F

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# **Product Identification Code**

Code	Pins										
	<b>A0</b>	A1	DQ7	DQ6	DQ5	DQ4	DQ3	DQ2	DQ1	DQ0	Data
Manufacturer	0	1	0	0	0	1	1	1	0	0	1C
Device Type	1	1	0	0	0	0	0	0	1	0	02
Continuation	0	0	0	1	1	1	1	1	1	1	7F
	1	0	0	1	1	1	1	1	1	1	7F

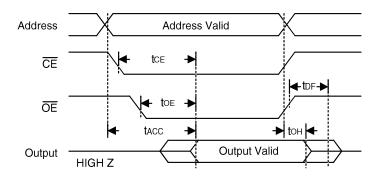


Figure 1. A.C. waveforms for read operation



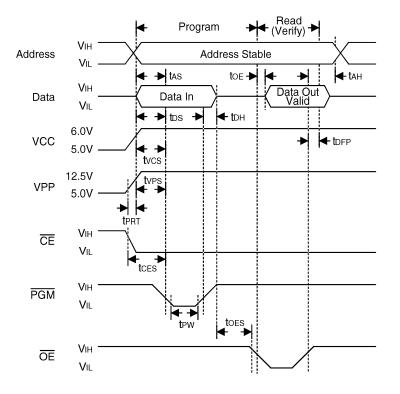
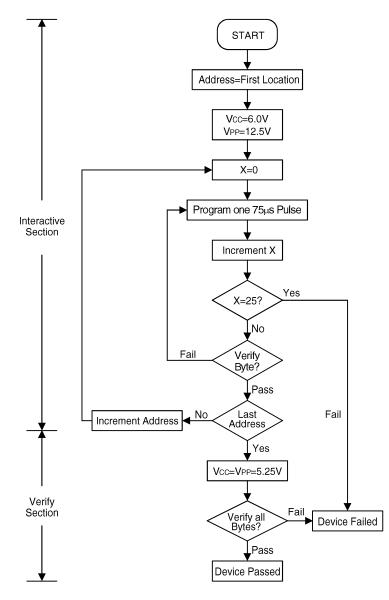
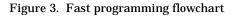


Figure 2. Programming waveforms

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Note: Either 105µs or 30µs pulse.



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